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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	-
Number of Macrocells	64
Number of Gates	-
Number of I/O	32
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a5-64-32-10vc48

GENERAL DESCRIPTION

The ispMACH™ 4A family from Lattice offers an exceptionally flexible architecture and delivers a superior Complex Programmable Logic Device (CPLD) solution of easy-to-use silicon products and software tools. The overall benefits for users are a guaranteed and predictable CPLD solution, faster time-to-market, greater flexibility and lower cost. The ispMACH 4A devices offer densities ranging from 32 to 512 macrocells with 100% utilization and 100% pin-out retention. The ispMACH 4A families offer 5-V (M4A5-xxx) and 3.3-V (M4A3-xxx) operation.

ispMACH 4A products are 5-V or 3.3-V in-system programmable through the JTAG (IEEE Std. 1149.1) interface. JTAG boundary scan testing also allows product testability on automated test equipment for device connectivity.

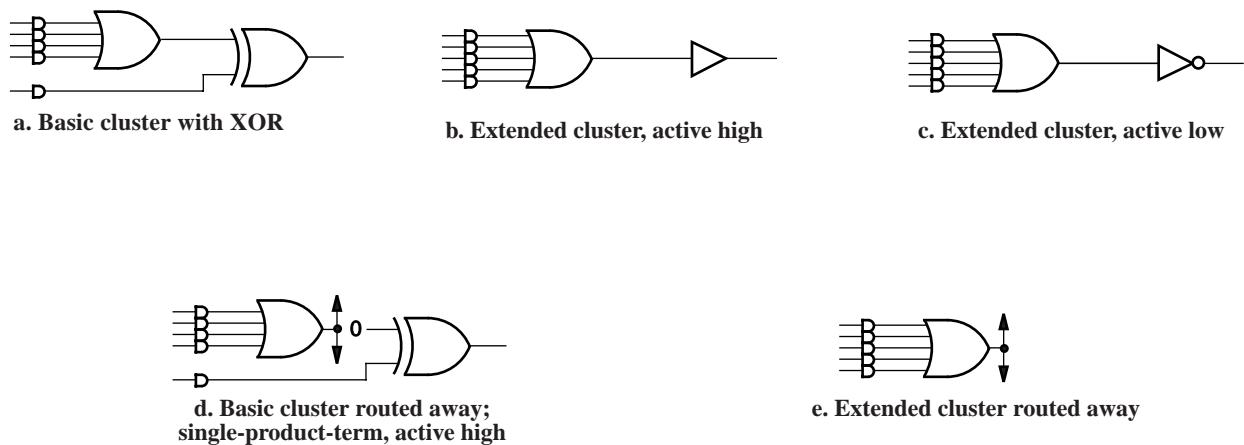
All ispMACH 4A family members deliver First-Time-Fit and easy system integration with pin-out retention after any design change and refit. For both 3.3-V and 5-V operation, ispMACH 4A products can deliver guaranteed fixed timing as fast as 5.0 ns t_{PD} and 182 MHz f_{CNT} through the SpeedLocking feature when using up to 20 product terms per output (Table 2).

Table 2. ispMACH 4A Speed Grades

Device	Speed Grade							
	-5	-55	-6	-65	-7	-10	-12	-14
M4A3-32	C				C, I	C, I	I	
M4A5-32								
M4A3-64/32		C			C, I	C, I	I	
M4A5-64/32								
M4A3-64/64		C			C, I	C, I	I	
M4A3-96		C			C, I	C, I	I	
M4A5-96								
M4A3-128		C			C, I	C, I	I	
M4A5-128								
M4A3-192			C		C, I	C, I	I	
M4A5-192								
M4A3-256/128		C		C	C, I	C, I	I	
M4A5-256/128				C	C	C, I	I	
M4A3-256/192					C	C, I	I	
M4A3-256/160								
M4A3-384				C		C, I	C, I	I
M4A3-512					C	C, I	C, I	I

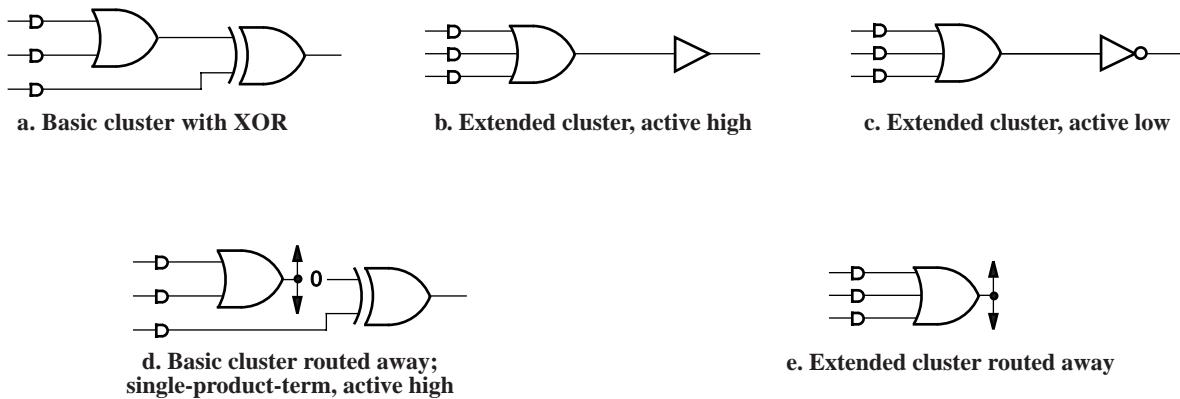
Note:

1. C = Commercial I = Industrial



17466G-007

Figure 3. Logic Allocator Configurations: Synchronous Mode



17466G-008

Figure 4. Logic Allocator Configurations: Asynchronous Mode

Note that the configuration of the logic allocator has absolutely no impact on the speed of the signal. All configurations have the same delay. This means that designers do not have to decide between optimizing resources or speed; both can be optimized.

If not used in the cluster, the extra product term can act in conjunction with the basic cluster to provide XOR logic for such functions as data comparison, or it can work with the D-, T-type flip-flop to provide for J-K, and S-R register operation. In addition, if the basic cluster is routed to another macrocell, the extra product term is still available for logic. In this case, the first XOR input will be a logic 0. This circuit has the flexibility to route product terms elsewhere without giving up the use of the macrocell.

Product term clusters do not “wrap” around a PAL block. This means that the macrocells at the ends of the block have fewer product terms available.

Table 8. Register/Latch Operation

Configuration	Input(s)	CLK/LE ¹	Q+
D-type Register	D=X	0, 1, ↓ (↑)	Q
	D=0	↑ (↓)	0
	D=1	↑ (↓)	1
T-type Register	T=X	0, 1, ↓ (↑)	Q
	T=0	↑ (↓)	Q
	T=1	↑ (↓)	Q̄
D-type Latch	D=X	1(0)	Q
	D=0	0(1)	0
	D=1	0(1)	1

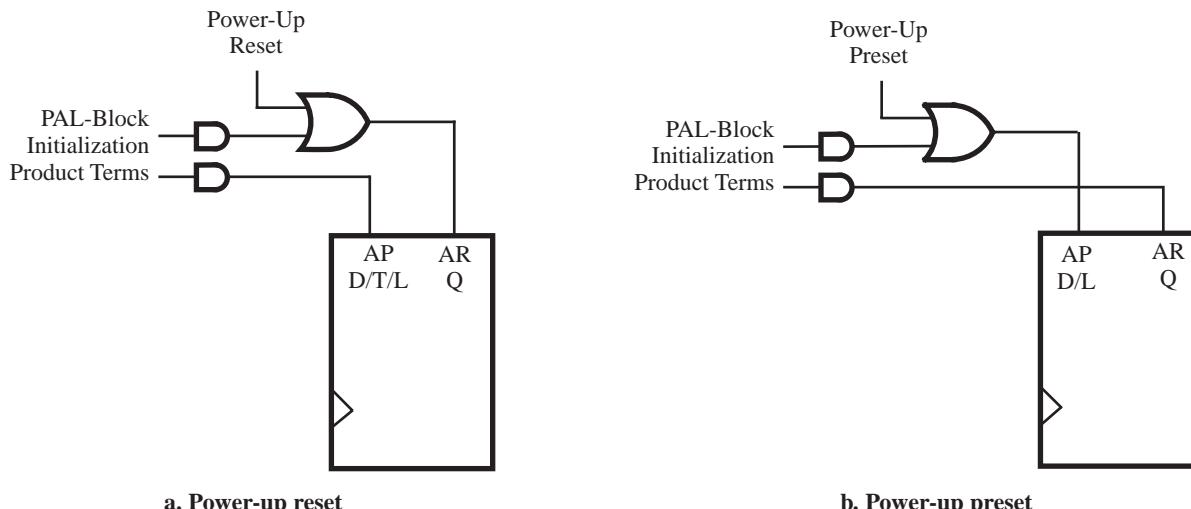
Note:

1. Polarity of CLK/LE can be programmed

Although the macrocell shows only one input to the register, the XOR gate in the logic allocator allows the D-, T-type register to emulate J-K, and S-R behavior. In this case, the available product terms are divided between J and K (or S and R). When configured as J-K, S-R, or T-type, the extra product term must be used on the XOR gate input for flip-flop emulation. In any register type, the polarity of the inputs can be programmed.

The clock input to the flip-flop can select any of the four PAL block clocks in synchronous mode, with the additional choice of either polarity of an individual product term clock in the asynchronous mode.

The initialization circuit depends on the mode. In synchronous mode (Figure 7), asynchronous reset and preset are provided, each driven by a product term common to the entire PAL block.



17466G-012

17466G-013

Figure 7. Synchronous Mode Initialization Configurations

Output Switch Matrix

The output switch matrix allows macrocells to be connected to any of several I/O cells within a PAL block. This provides high flexibility in determining pinout and allows design changes to occur without effecting pinout.

In ispMACH 4A devices with 2:1 Macrocell-I/O cell ratio, each PAL block has twice as many macrocells as I/O cells. The ispMACH 4A output switch matrix allows for half of the macrocells to drive I/O cells within a PAL block, in combinations according to Figure 9. Each I/O cell can choose from eight macrocells; each macrocell has a choice of four I/O cells. The ispMACH 4A devices with 1:1 Macrocell-I/O cell ratio allow each macrocell to drive one of eight I/O cells (Figure 9).

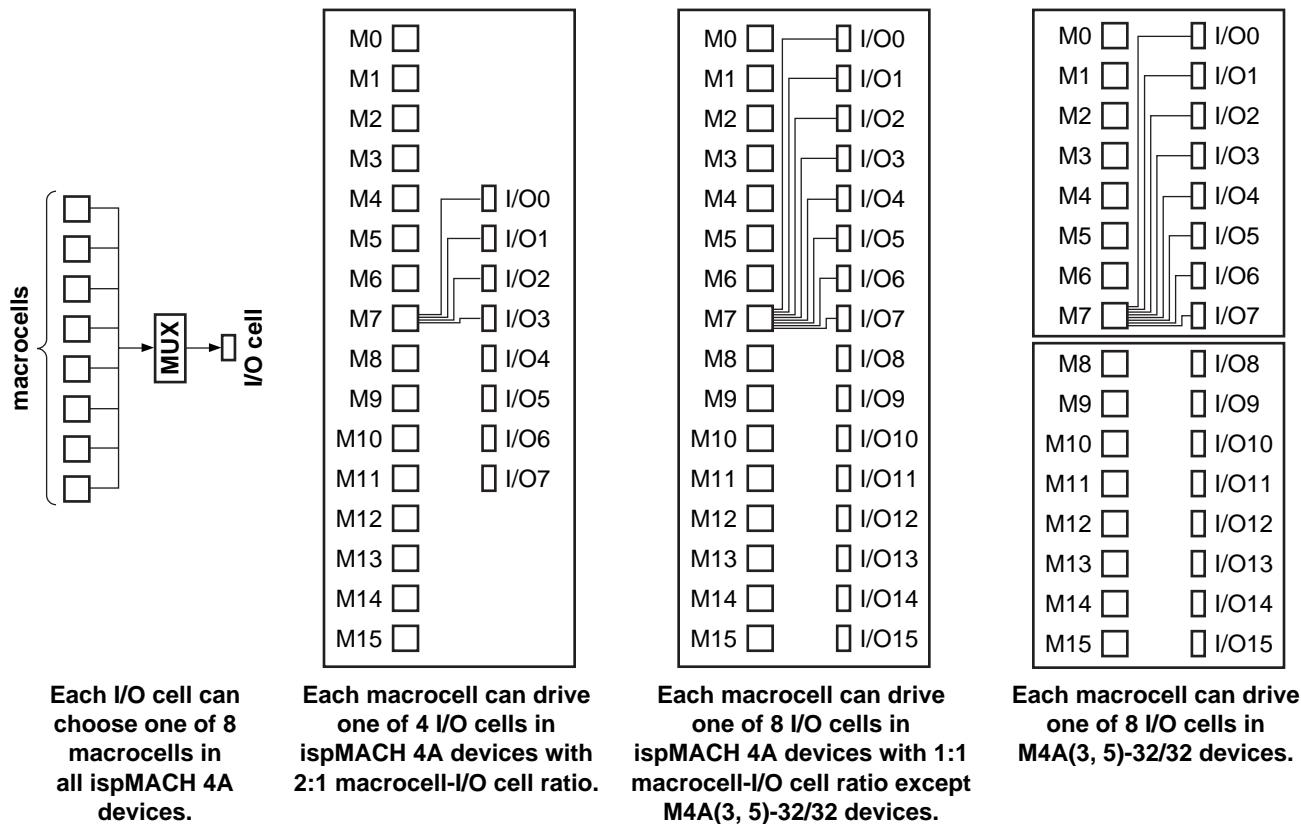


Figure 9. ispMACH 4A Output Switch Matrix

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routable to I/O Cells
M0, M1	I/00, I/05, I/06, I/07
M2, M3	I/00, I/01, I/06, I/07
M4, M5	I/00, I/01, I/02, I/07
M6, M7	I/00, I/01, I/02, I/03
M8, M9	I/01, I/02, I/03, I/04
M10, M11	I/02, I/03, I/04, I/05

Table 10. Output Switch Matrix Combinations for ispMACH 4A Devices with 2:1 Macrocell-I/O Cell Ratio

Macrocell	Routeable to I/O Cells
M12, M13	I/03, I/04, I/05, I/06
M14, M15	I/04, I/05, I/06, I/07

I/O Cell	Available Macrocells
I/00	M0, M1, M2, M3, M4, M5, M6, M7
I/01	M2, M3, M4, M5, M6, M7, M8, M9
I/02	M4, M5, M6, M7, M8, M9, M10, M11
I/03	M6, M7, M8, M9, M10, M11, M12, M13
I/04	M8, M9, M10, M11, M12, M13, M14, M15
I/05	M0, M1, M10, M11, M12, M13, M14, M15
I/06	M0, M1, M2, M3, M12, M13, M14, M15
I/07	M0, M1, M2, M3, M4, M5, M14, M15

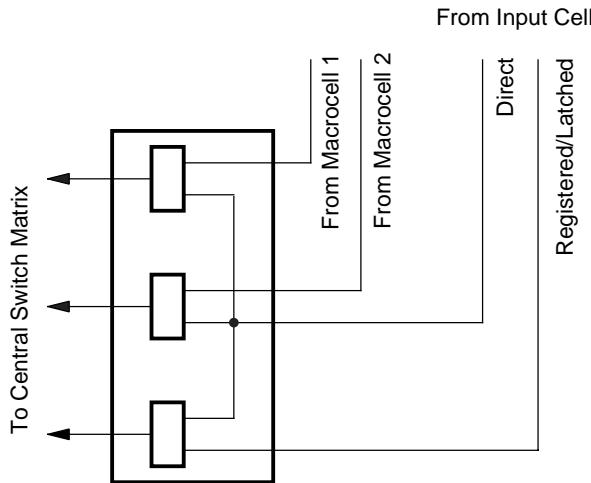
Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routeable to I/O Cells							
M0	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M1	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M2	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M3	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M4	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M5	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M6	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M7	I/00	I/01	I/02	I/03	I/04	I/05	I/06	I/07
M8	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M9	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M10	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M11	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M12	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M13	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M14	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015
M15	I/08	I/09	I/010	I/011	I/012	I/013	I/014	I/015

I/O Cell	Available Macrocells							
I/00	M0	M1	M2	M3	M4	M5	M6	M7
I/01	M0	M1	M2	M3	M4	M5	M6	M7
I/02	M0	M1	M2	M3	M4	M5	M6	M7
I/03	M0	M1	M2	M3	M4	M5	M6	M7
I/04	M0	M1	M2	M3	M4	M5	M6	M7
I/05	M0	M1	M2	M3	M4	M5	M6	M7
I/06	M0	M1	M2	M3	M4	M5	M6	M7
I/07	M0	M1	M2	M3	M4	M5	M6	M7

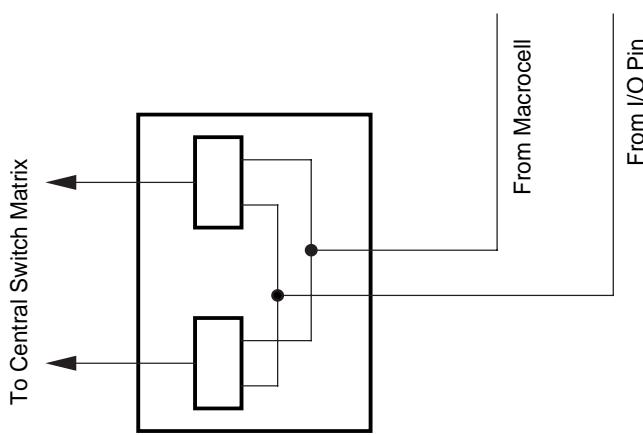
Input Switch Matrix

The input switch matrix (Figures 12 and 13) optimizes routing of inputs to the central switch matrix. Without the input switch matrix, each input and feedback signal has only one way to enter the central switch matrix. The input switch matrix provides additional ways for these signals to enter the central switch matrix.



17466G-002

Figure 12. ispMACH 4A with 2:1 Macrocell-I/O Cell Ratio - Input Switch Matrix



17466G-003

Figure 13. ispMACH 4A with 1:1 Macrocell-I/O Cell Ratio - Input Switch Matrix

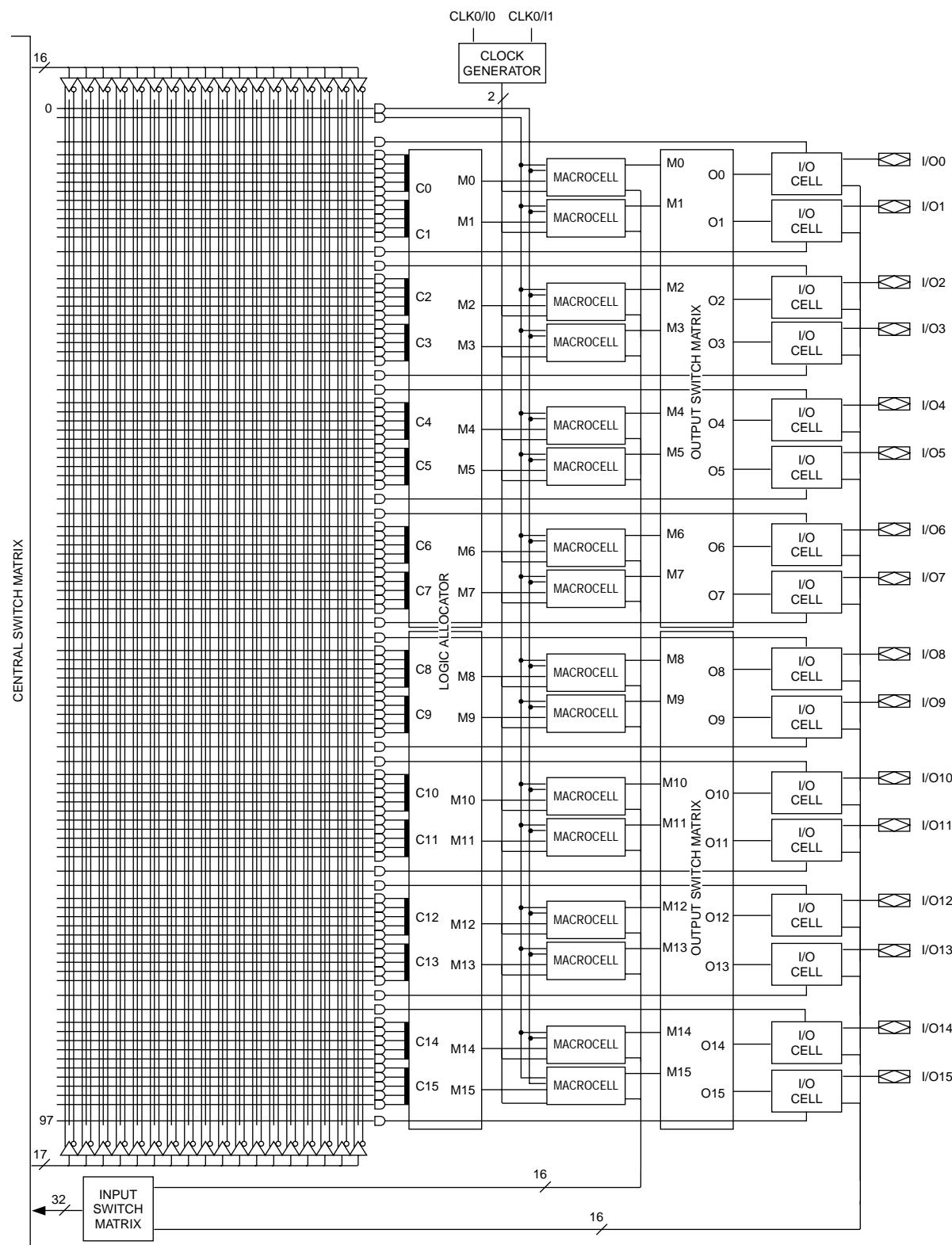
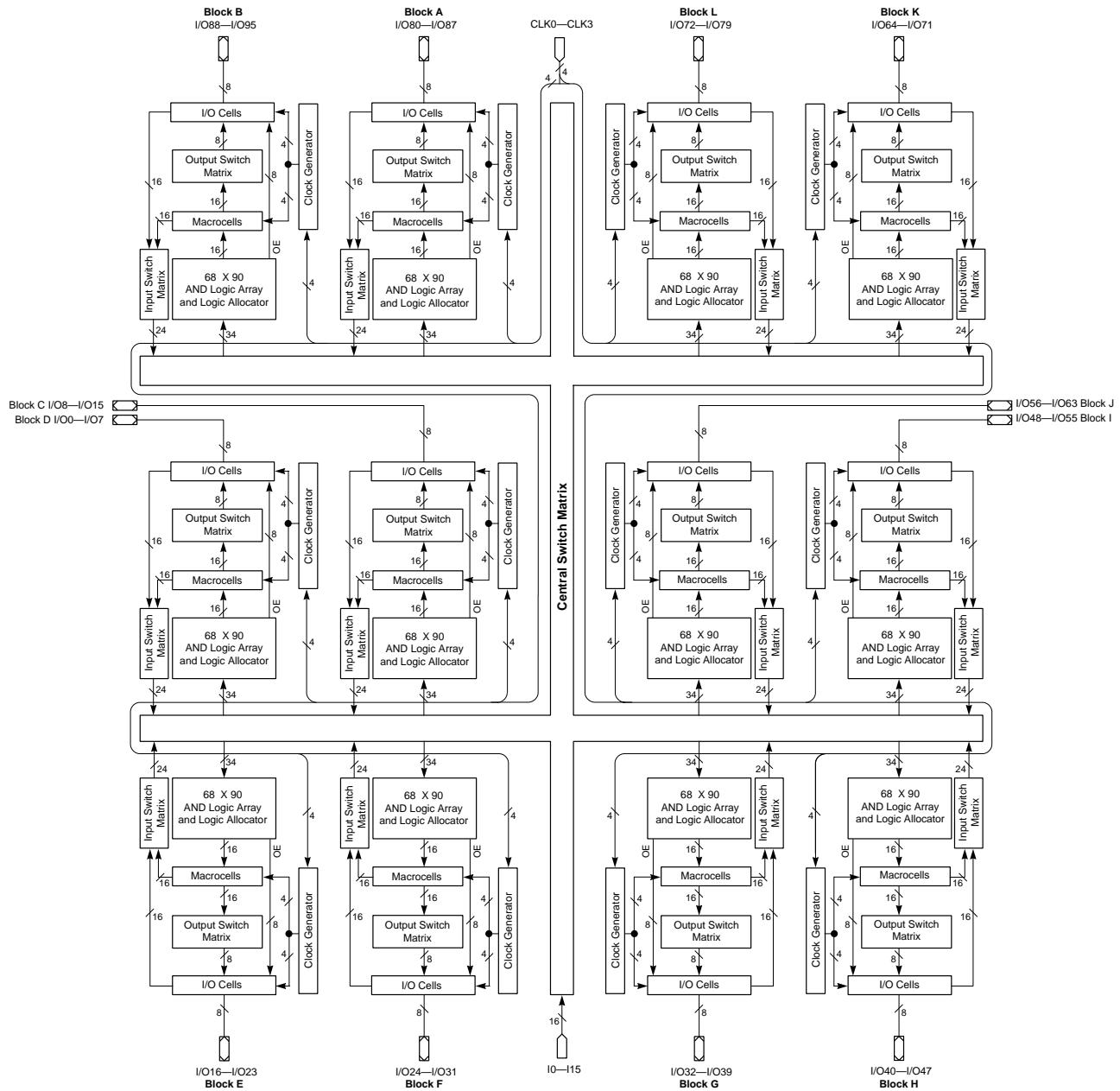


Figure 18. PAL Block for M4A (3,5)-32/32

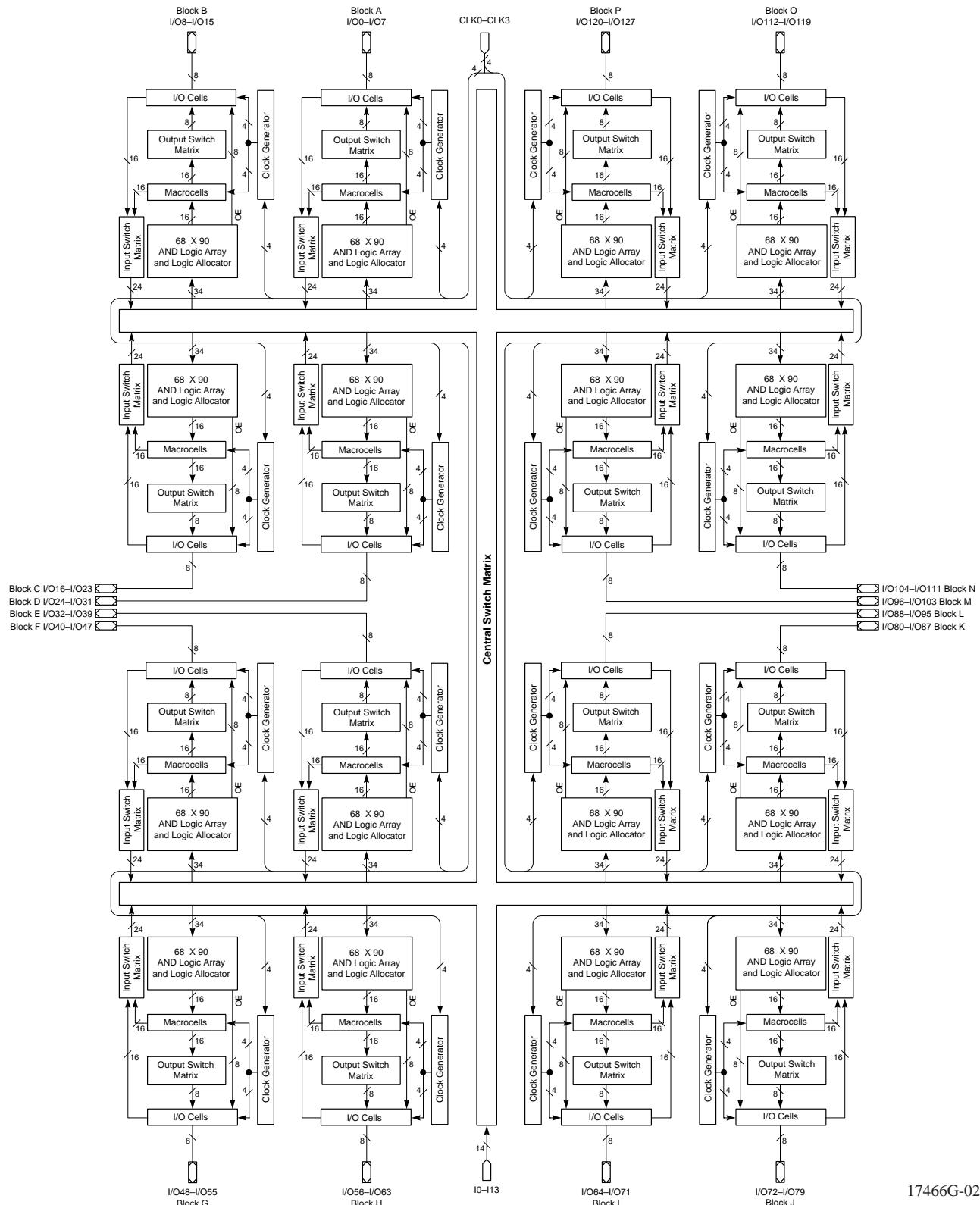
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BLOCK DIAGRAM – M4A(3,5)-192/96

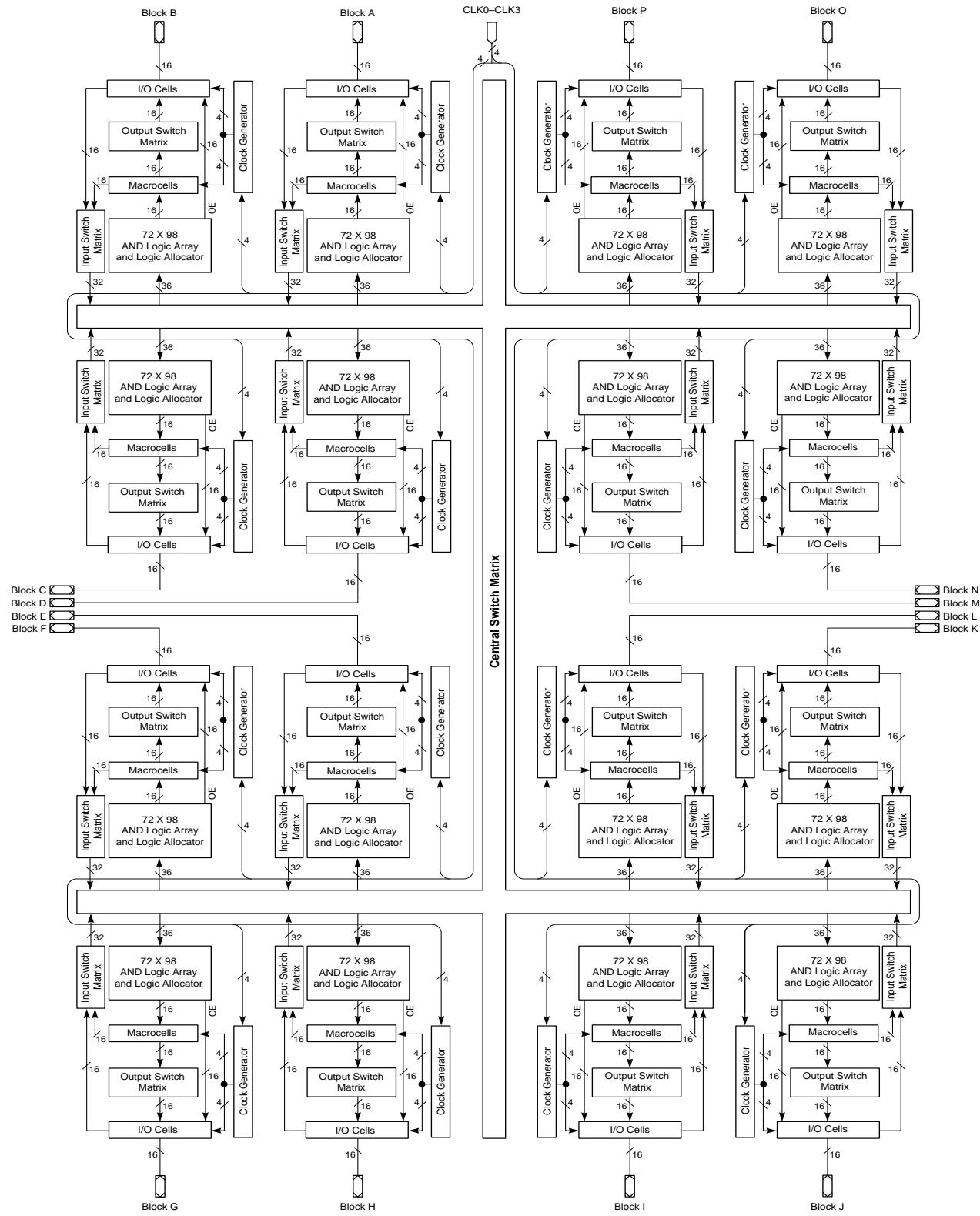


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BLOCK DIAGRAM – M4A(3,5)-256/128



BLOCK DIAGRAM – M4A3-256/160, M4A3-256/192



17466G-050

ABSOLUTE MAXIMUM RATINGS

M4A5

Storage Temperature.....	-65°C to +150°C
Ambient Temperature with Power Applied.....	-55°C to +100°C
Device Junction Temperature.....	+130°C
Supply Voltage with Respect to Ground	-0.5 V to +7.0 V
DC Input Voltage	-0.5 V to V_{CC} + 0.5 V
Static Discharge Voltage.....	2000 V
Latchup Current ($T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)	200 mA
<i>Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.</i>	

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)	
Operating in Free Air.....	0°C to +70°C
Supply Voltage (V_{CC}) with Respect to Ground.....	+4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)	
Operating in Free Air.....	-40°C to +85°C
Supply Voltage (V_{CC}) with Respect to Ground.....	+4.50 V to +5.5 V
<i>Operating ranges define those limits between which the functionality of the device is guaranteed.</i>	

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	$I_{OH} = -3.2 \text{ mA}$, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL}	2.4			V
		$I_{OH} = -100 \mu\text{A}$, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL}		3.3	3.6	V
V_{OL}	Output LOW Voltage	$I_{OL} = 24 \text{ mA}$, $V_{CC} = \text{Min}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 1)			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 2)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 2)			0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}$, $V_{CC} = \text{Max}$ (Note 3)			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}$, $V_{CC} = \text{Max}$ (Note 3)			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25 \text{ V}$, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}$, $V_{CC} = \text{Max}$, $V_{IN} = V_{IH}$ or V_{IL} (Note 3)			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}$, $V_{CC} = \text{Max}$ (Note 4)	-30		-160	mA

Notes:

1. Total I_{OL} for one PAL block should not exceed 64 mA.
2. These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.
3. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
4. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. $V_{OUT} = 0.5 \text{ V}$ has been chosen to avoid test problems caused by tester ground degradation.

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES¹

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Input Register Delays with ZHT Option:																		
t _{SIRZ}	Input register setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HIRZ}	Input register hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
Input Latch Delays with ZHT Option:																		
t _{SILZ}	Input latch setup time - ZHT	6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0		ns
t _{HILZ}	Input latch hold time - ZHT	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{PDIL} Z _i	Transparent input latch to internal feedback - ZHT		6.0		6.0		6.0		6.0		6.0		6.0		6.0		6.0	ns
Output Delays:																		
t _{BUF}	Output buffer delay		1.5		1.5		1.8		2.0		2.5		3.0		3.0		3.0	ns
t _{SLW}	Slow slew rate delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t _{EA}	Output enable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
t _{ER}	Output disable time		7.5		7.5		8.5		8.5		9.5		10.0		12.0		15.0	ns
Power Delay:																		
t _{PL}	Power-down mode delay adder		2.5		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
Reset and Preset Delays:																		
t _{SRI}	Asynchronous reset or preset to internal register output		7.5		7.7		8.0		8.0		9.5		11.0		13.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		9.0		9.2		10.0		10.0		12.0		14.0		16.0		19.0	ns
t _{SRR}	Asynchronous reset and preset register recovery time	7.0		7.0		7.5		7.5		8.0		8.0		10.0		15.0		ns
t _{SRW}	Asynchronous reset or preset width	7.0		7.0		8.0		8.0		10.0		10.0		12.0		15.0		ns
Clock/LE Width:																		
t _{WLS}	Global clock width low	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WHS}	Global clock width high	2.0		2.0		2.5		2.5		3.0		4.0		5.0		6.0		ns
t _{WIA}	Product term clock width low	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{WHA}	Product term clock width high	3.0		3.0		3.5		3.5		4.0		5.0		8.0		9.0		ns
t _{GWS}	Global gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns
t _{GWA}	Product term gate width low (for low transparent) or high (for high transparent)	4.0		4.0		4.5		4.5		5.0		5.0		6.0		9.0		ns
t _{WIRL}	Input register clock width low	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIRH}	Input register clock width high	3.0		3.0		3.5		3.5		4.0		5.0		6.0		6.0		ns
t _{WIL}	Input latch gate width	4.0		4.0		4.5		4.5		5.0		5.0		6.0		6.0		ns

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES¹

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Frequency:																		
f_{MAXS}	External feedback, D-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COS})$	143		133		125		118		95.2		87.0		74.1		60.6		MHz
	External feedback, T-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COS})$	125		125		118		111		87.0		80.0		69.0		57.1		MHz
	Internal feedback (f_{CNT}), D-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COS})$	182		167		160		154		125		118		95.0		74.1		MHz
	Internal feedback (f_{CNT}), T-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COS})$	154		154		148		143		111		105		87.0		69.0		MHz
	No feedback ² , Min of $1/(t_{WLS} + t_{WHS})$, $1/(t_{SS} + t_{HS})$ or $1/(t_{SST} + t_{HS})$	250		250		200		200		154		125		100		83.3		MHz
f_{MAXA}	External feedback, D-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{COA})$	111		111		108		100		83.3		66.7		55.6		43.5		MHz
	External feedback, T-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SAT} + t_{COA})$	105		105		102		95.2		76.9		62.5		52.6		41.7		MHz
	Internal feedback (f_{CNTA}), D-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{COA})$	133		133		125		125		105		83.3		66.7		50.0		MHz
	Internal feedback (f_{CNTA}), T-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SAT} + t_{COA})$	125		125		125		118		95.2		76.9		62.5		47.6		MHz
	No feedback ² , Min of $1/(t_{WLA} + t_{WHA})$, $1/(t_{SA} + t_{HA})$ or $1/(t_{SAT} + t_{HA})$	167		167		143		143		125		100		62.5		55.6		MHz
f_{MAXI}	Maximum input register frequency, Min of $1/(t_{WIRH} + t_{WIRL})$ or $1/(t_{SIRS} + t_{HIRS})$	167		167		143		143		125		100		83.3		83.3		MHz

Notes:

- See "Switching Test Circuit" document on the Literature Download page of the Lattice web site.
- This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.

CAPACITANCE¹

Parameter Symbol	Parameter Description	Test Conditions		Typ	Unit
C_{IN}	Input capacitance	$V_{IN}=2.0\text{ V}$	3.3 V or 5 V, 25°C, 1 MHz	6	pF
$C_{I/O}$	Output capacitance	$V_{OUT}=2.0\text{ V}$	3.3 V or 5 V, 25°C, 1 MHz	8	pF

Note:

- These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where this parameter may be affected.

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected “typical” pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power-Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power.

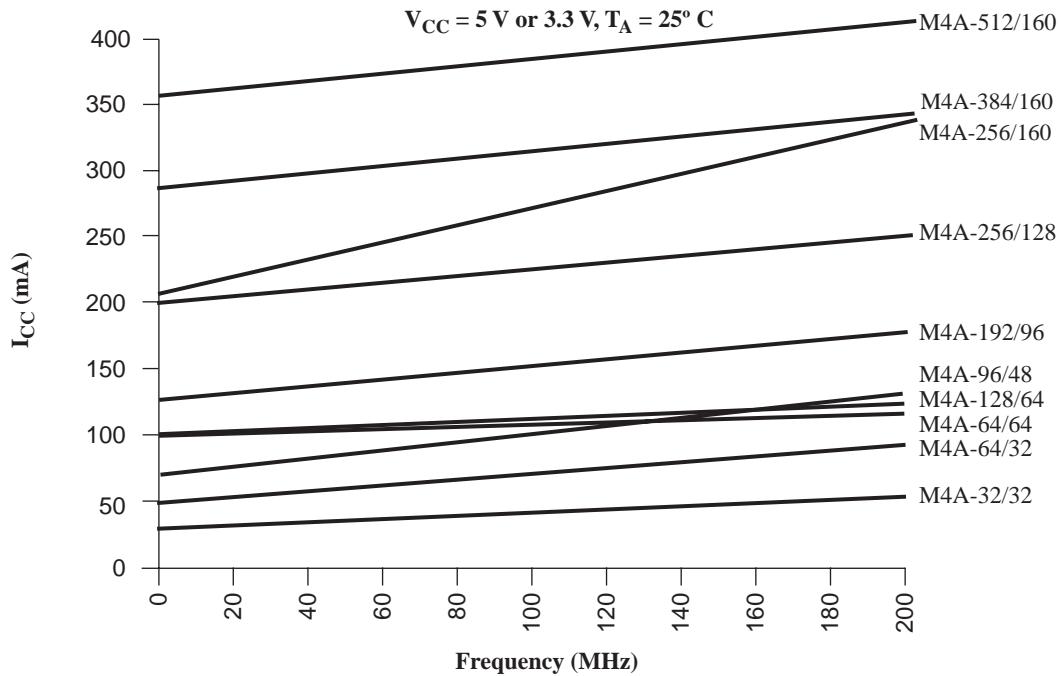


Figure 19. ispMACH 4A I_{CC} Curves at High Speed Mode

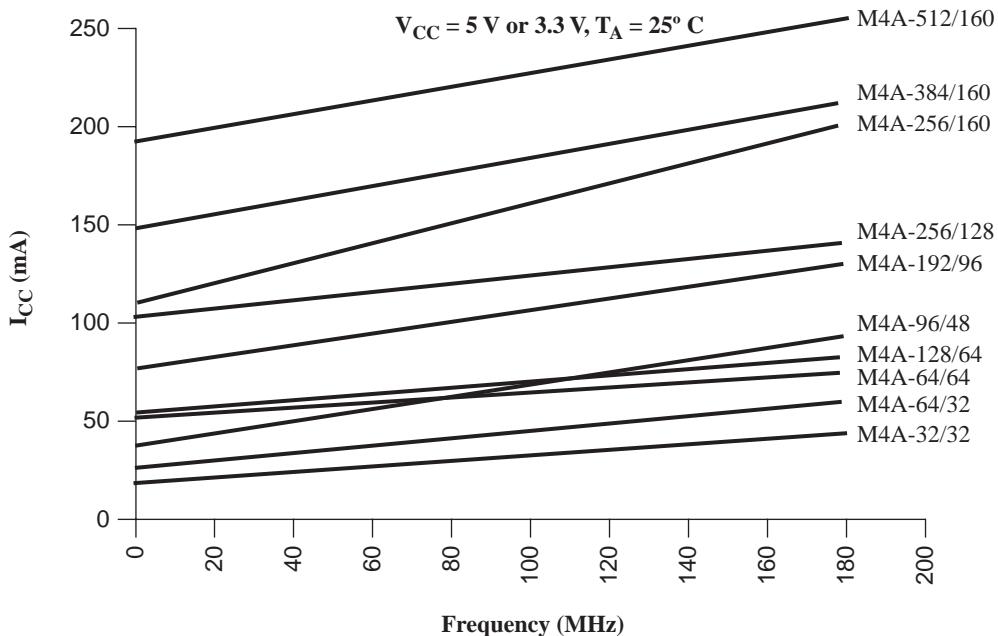
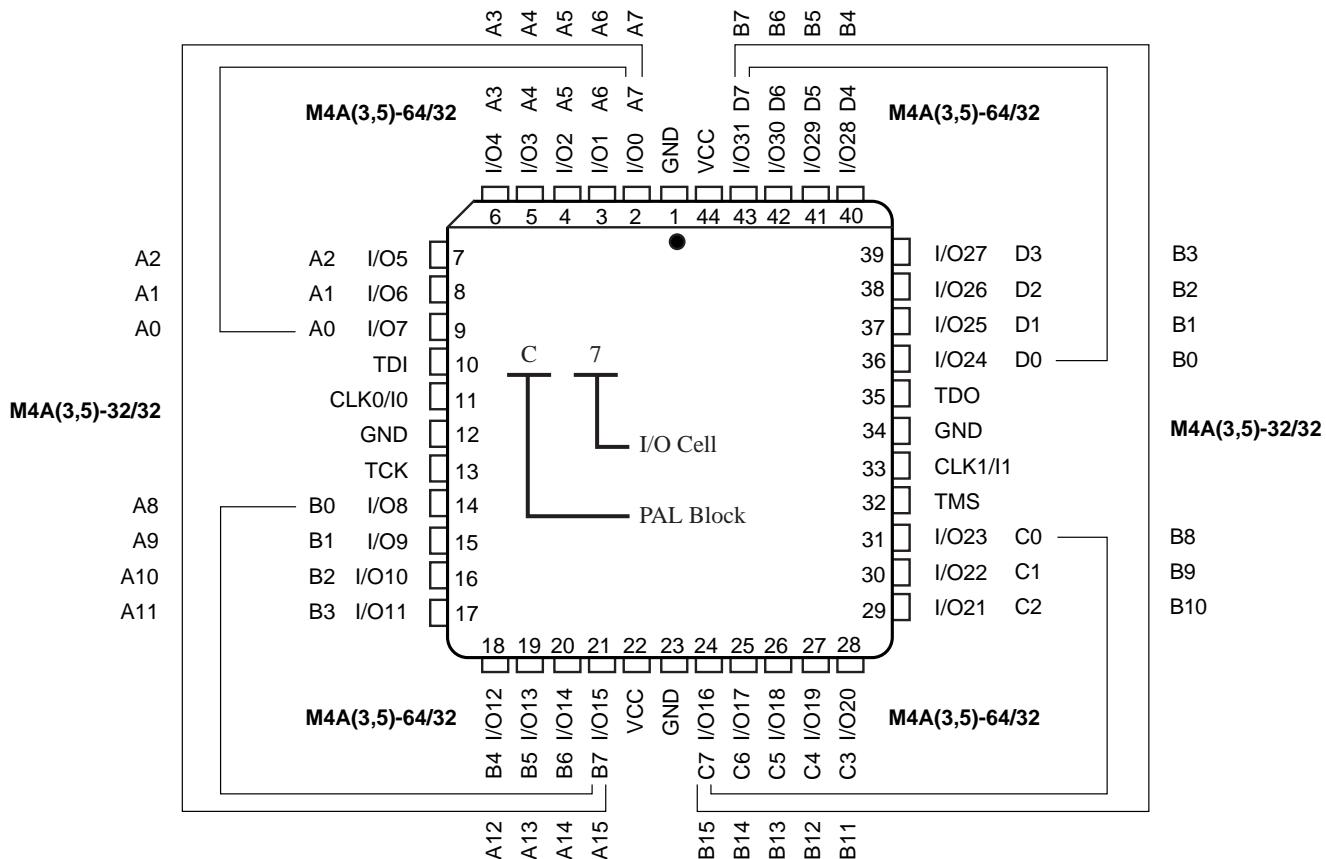


Figure 20. ispMACH 4A I_{CC} Curves at Low Power Mode

44-PIN PLCC CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

44-Pin PLCC



17466G-026

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

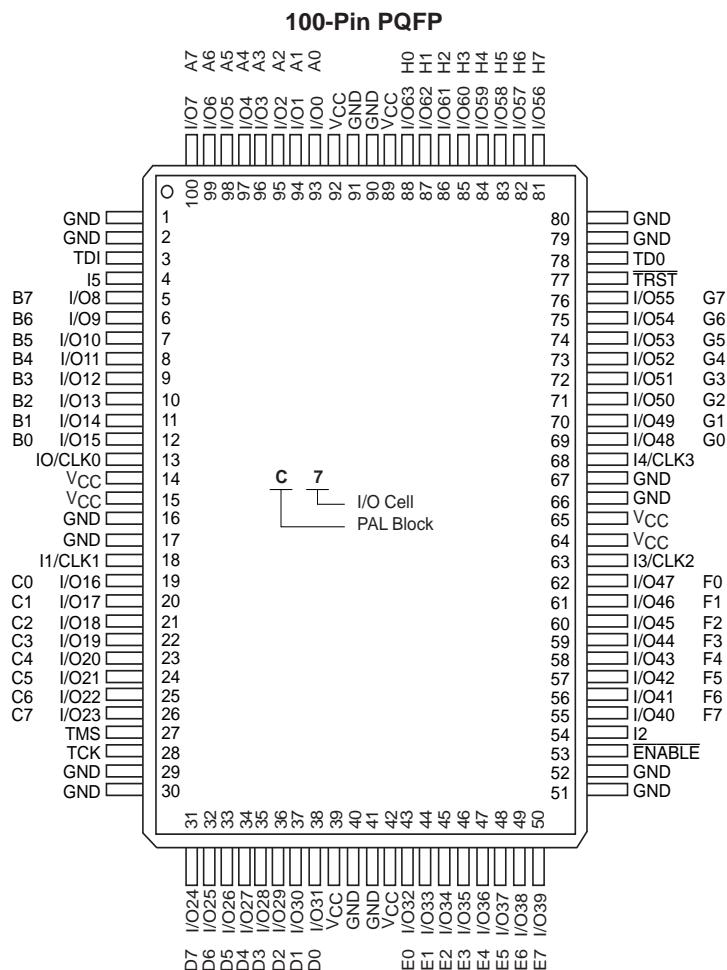
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-128/64)

Top View



17466G-031

PIN DESIGNATIONS

I/CLK = Input or Clock

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

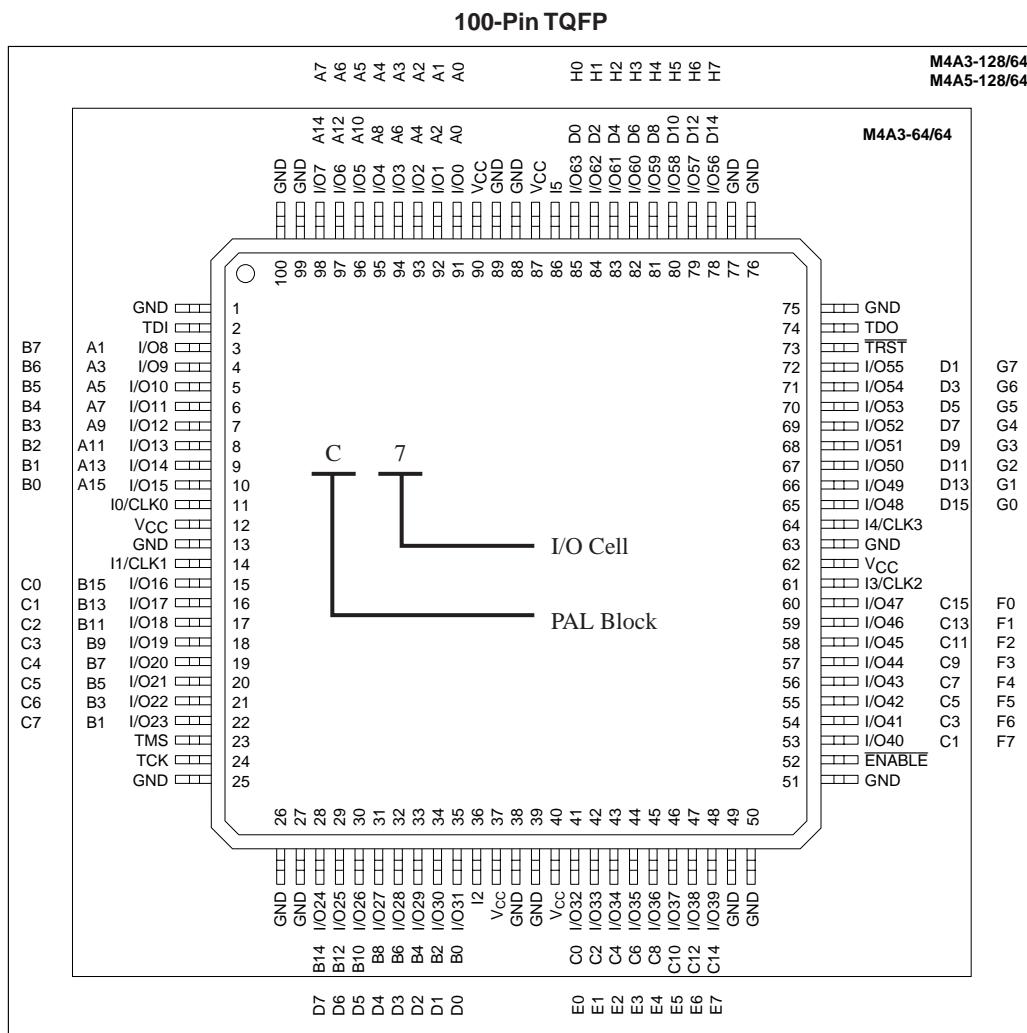
TDO = Test Data Out

TRST = Test Reset

ENABLE = Program

100-PIN TQFP CONNECTION DIAGRAM (M4A3-64/64 AND M4A(3,5)-128/64)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

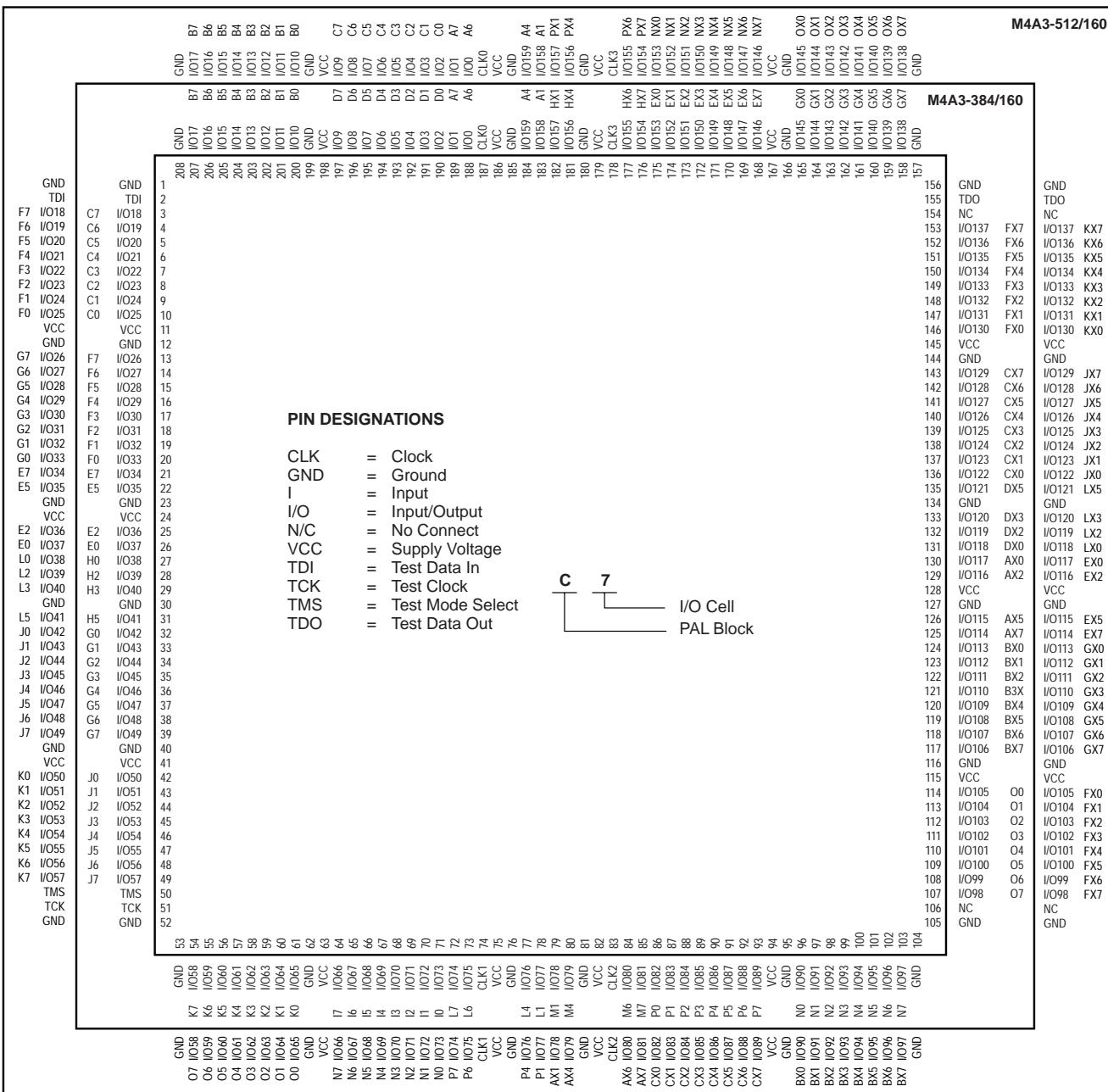
TRST = Test Reset

ENABLE = Program

208-PIN PQFP CONNECTION DIAGRAM (M4A3-384/160 AND M4A3-512/160)

Top View

208-Pin PQFP



17466Ga-044

ispMACH 4A PRODUCT ORDERING INFORMATION

ispMACH 4A Devices Commercial and Industrial - 3.3V and 5V

Lattice programmable logic products are available with several ordering options. The order number (Valid Combination) is formed by a combination of:

M4A3-	256 / 128	-7	Y	C	T ₄₈	= 48-pin TQFP for M4A3-32/32 or M4A3-64/32 M4A5-32/32 or M4A5-64/32
FAMILY TYPE						OPERATING CONDITIONS
M4A3- = ispMACH 4A Family Low Voltage Advanced Feature (3.3-V V _{CC})						C = Commercial (0°C to +70°C)
M4A5- = ispMACH 4A Family Advanced Feature (5-V V _{CC})						I = Industrial (-40°C to +85°C)
MACROCELL DENSITY						PACKAGE TYPE
32 = 32 Macrocells	192 = 192 Macrocells					SA = Ball Grid Array (BGA)
64 = 64 Macrocells	256 = 256 Macrocells					J = Plastic Leaded Chip Carrier (PLCC)
96 = 96 Macrocells	384 = 384 Macrocells					JN = Lead-free Plastic Leaded Chip Carrier (PLCC)
128 = 128 Macrocells	512 = 512 Macrocells					V = Thin Quad Flat Pack (TQFP)
I/Os						VN = Lead-free Thin Quad Flat Pack (TQFP)
/32 = 32 I/Os in 44-pin PLCC, 44-pin TQFP or 48-pin TQFP						Y = Plastic Quad Flat Pack (PQFP)
/48 = 48 I/Os in 100-pin TQFP						YN = Lead-free Plastic Quad Flat Pack (PQFP)
/64 = 64 I/Os in 100-pin TQFP, 100-pin PQFP, or 100-ball caBGA						FA = Fine-pitch Ball Grid Array (fpBGA)
/96 = 96 I/Os in 144-pin TQFP or 144-ball fpBGA						FAN = Lead-free Fine-pitch Ball Grid Array (fpBGA)
/128 = 128 I/Os in 208-pin PQFP, 256-ball BGA or 256-ball fpBGA						CA = Chip-array Ball Grid Array (caBGA)
/160 = 160 I/Os in 208-pin PQFP						
/192 = 192 I/Os in 256-ball BGA or 256-ball fpBGA						
/256 = 256 I/Os in 388-ball fpBGA						
SPEED						
						-5 = 5.0 ns t _{PD}
						-55 = 5.5 ns t _{PD}
						-6 = 6.0 ns t _{PD}
						-65 = 6.5 ns t _{PD}
						-7 = 7.5 ns t _{PD}
						-10 = 10 ns t _{PD}
						-12 = 12 ns t _{PD}
						-14 = 14 ns t _{PD}

*Package obsolete, contact factory.

Conventional Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	JC, VC, VC48
M4A3-64/32		JC, VC, VC48
M4A3-64/64		VC
M4A3-96/48		VC
M4A3-128/64		YC, VC, CAC
M4A3-192/96	-6, -7, -10	VC, FAC
M4A3-256/128	-55, -65 ¹ , -7, -10	YC, FAC, SAC
M4A3-256/160		YC
M4A3-256/192	-7, -10	FAC
M4A3-384/160		YC
M4A3-384/192	-65, -10, -12	SAC, FAC
M4A3-512/160		YC
M4A3-512/192	-7, -10, -12	FAC
M4A3-512/256		FAC

3.3V Industrial Combinations		
M4A3-32/32		JI, VI, VI48
M4A3-64/32		JI, VI, VI48
M4A3-64/64		VI
M4A3-96/48		VI
M4A3-128/64		YI, VI, CAI
M4A3-192/96		VI, FAI
M4A3-256/128		YI, FAI, SAI
M4A3-256/160		YI
M4A3-256/192	-10, -12	FAI
M4A3-384/160		YI
M4A3-384/192		FAI
M4A3-512/160		YI
M4A3-512/192	-10, -12, -14	FAI
M4A3-512/256		FAI

1. Use 5.5ns for new designs.

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10,	JC, VC, VC48
M4A5-64/32		JC, VC, VC48
M4A5-96/48	-55, -7, -10	VC
M4A5-128/64		YC, VC
M4A5-192/96	-6, -7, -10	VC
M4A5-256/128	-65, -7, -10	YC

5V Industrial Combinations		
M4A5-32/32	-7, -10, -12	JI, VI, VI48
M4A5-64/32		JI, VI, VI48
M4A5-96/48	-7, -10, -12	VI
M4A5-128/64		YI, VI
M4A5-192/96	-7, -10, -12	VI
M4A5-256/128	-10, -12	YI

Lead-free Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A3-64/32		VNC, VNC48, JNC
M4A3-64/64	-55, -7, -10	VNC
M4A3-128/64		VNC
M4A3-192/96	-6, -7, -10	VNC
M4A3-256/128	-55, -7, -10	FANC, YNC
M4A3-256/160		YNC
M4A3-256/192	-7, -10	FANC
M4A3-384/192	-65, -10, -12	FANC
M4A3-512/192	-7, -10, -12	FANC

3.3V Industrial Combinations		
M4A3-32/32		VNI, VNI48, JNI
M4A3-64/32	-7, -10, -12	VNI, VNI48, JNI
M4A3-64/64		VNI
M4A3-128/64		VNI
M4A3-192/96		VNI
M4A3-256/128	-10, -12	FANI, YNI
M4A3-256/160		YNI
M4A3-256/192		FANI
M4A3-384/192	-10, -12, -14	FANI
M4A3-512/192		FANI

5V Commercial Combinations		
M4A5-32/32	-5, -7, -10	VNC, VNC48, JNC
M4A5-64/32		VNC, VNC48, JNC
M4A5-96/48	-55, -7, -10	VNC
M4A5-128/64		VNC, YNC
M4A5-192/96	-6, -7, -10	VNC
M4A5-256/128	-65, -7, -10	YNC

5V Industrial Combinations		
M4A5-32/32		VNI, VNI48, JNI
M4A5-64/32	-7, -10, -12	VNI, VNI48, JNI
M4A5-96/48		VNI
M4A5-128/64		VNI, YNI
M4A5-192/96		VNI
M4A5-256/128		YNI

Most ispMACH devices are dual-marked with both Commercial and Industrial grades. The Industrial speed grade is slower, i.e., M4A3-256/128-7YC-10YI

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local Lattice sales office to confirm availability of specific valid combinations and to check on newly released combinations.